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June 2014

FDMA530PZ

Single P-Channel PowerTrench® MOSFET –30V, –6.8A, 35m Ω

Features

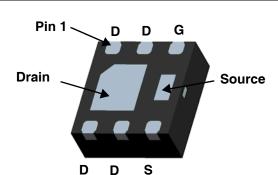
- Max $r_{DS(on)}$ = 35m Ω at V_{GS} = -10V, I_D = -6.8A
- Max $r_{DS(on)}$ = 65m Ω at V_{GS} = -4.5V, I_D = -5.0A
- Low profile 0.8mm maximum in the new package MicroFET 2X2 mm
- HBM ESD protection level > 3kV typical (Note 3)
- Free from halogenated compounds and antimony oxides
- RoHS Compliant

General Description

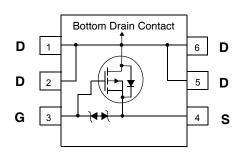
This device is designed specifically for battery charge or load switching in cellular handset and other ultraportable applications. It features a MOSFET with low on-state resistance.

The MicroFET 2X2 package offers exceptional thermal performance for its physical size and is well suited to linear mode applications.





MicroFET 2X2 (Bottom View)



MOSFET Maximum Ratings T_A = 25°C unless otherwise noted

Symbol	Parameter	Ratings	Units	
V _{DS}	Drain to Source Voltage			V
V _{GS}	Gate to Source Voltage		±25	V
I _D	Drain Current -Continuous	Current -Continuous (Note 1a)		^
	-Pulsed		-24	A
D	Power Dissipation	(Note 1a)	2.4	10/
P_{D}	Power Dissipation	(Note 1b)	0.9	W
T _J , T _{STG}	Operating and Storage Junction Temperature Range		-55 to +150	°C

Thermal Characteristics

$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1a)	52	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1b)	145	C/VV

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
530	FDMA530PZ	MicroFET 2X2	7"	8mm	3000 units

Electrical Characteristics T_J = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Characteristics						
BV_{DSS}	Drain to Source Breakdown Voltage	$I_D = -250 \mu A, V_{GS} = 0 V$	-30			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	I_D = -250 μ A, referenced to 25°C		-23		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -24V, V_{GS} = 0V$			-1	μА
I _{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 25V, V_{DS} = 0V$			±10	μА

On Characteristics

V _{GS(th)}	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = -250 \mu A$	-1	-2.1	-3	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D = -250\mu\text{A}$, referenced to 25°C		5.4		mV/°C
		$V_{GS} = -10V, I_D = -6.8A$		30	35	
r _{DS(on)}	r _{DS(on)} Static Drain to Source On Resistance	$V_{GS} = -4.5V$, $I_D = -5.0A$		52	65	mΩ
		$V_{GS} = -10V$, $I_D = -6.8A$, $T_J = 125$ °C		43	63	
g _{FS}	Forward Transconductance	$V_{DS} = -10V, I_D = -6.8A$		17		S

Dynamic Characteristics

C _{iss}	Input Capacitance	45)/)/ 0)/		805	1070	pF
C _{oss}	Output Capacitance	V _{DS} = –15V, V _{GS} = 0V, f = 1MHz		155	210	pF
C _{rss}	Reverse Transfer Capacitance	1 - 111112		130	195	pF
Rg	Gate Resistance		1	18	38	Ω

Switching Characteristics

t _{d(on)}	Turn-On Delay Time		6	12	ns
t _r	Rise Time	$V_{DD} = -15V$, $I_{D} = -6.8A$ $V_{GS} = -10V$, $R_{GEN} = 6\Omega$	21	34	ns
t _{d(off)}	Turn-Off Delay Time	$V_{GS} = -10V$, $R_{GEN} = 602$	43	69	ns
t _f	Fall Time		31	50	ns
Q _g	Total Gate Charge	V _{GS} = -10V	16	24	nC
Qg	Total Gate Charge	$V_{GS} = -5V$ $V_{DD} = -15V$ $I_{D} = -6.8A$	9	11	nC
Q_{gs}	Gate to Source Gate Charge	I _D = -0.6A	3.1		nC
Q_{gd}	Gate to Drain "Miller" Charge		4.5		nC

Drain-Source Diode Characteristics

Is	Maximum Continuous Drain-Source Diode Forward Current				-2	Α
V_{SD}	Source to Drain Diode Forward Voltage $V_{GS} = 0V$, $I_S = -2A$			-0.8	-1.2	V
t _{rr}	Reverse Recovery Time	I _F = -6.8A, di/dt = 100A/μs		24	36	ns
Q _{rr}	Reverse Recovery Charge	-1 _F = -0.6A, αι/αι = 100A/μS		19	29	nC

1: $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins.



a. 52°C/W when mounted on a 1 in² pad of 2 oz copper



b.145°C/W when mounted on a minimum pad of 2 oz copper

- 2: Pulse Test: Pulse Width < 300µs, Duty cycle < 2.0%.
 3: The diode connected between the gate and the source serves only as protection against ESD. No gate overvoltage rating is implied.

Typical Characteristics T_J = 25°C unless otherwise noted

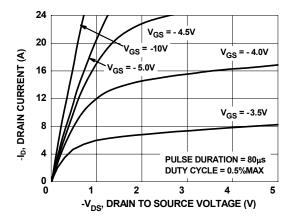


Figure 1. On-Region Characteristics

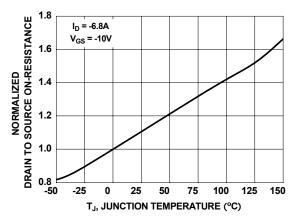


Figure 3. Normalized On-Resistance vs Junction Temperature

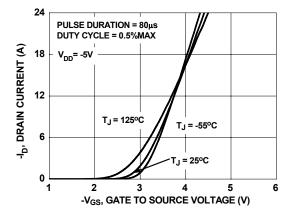


Figure 5. Transfer Characteristics

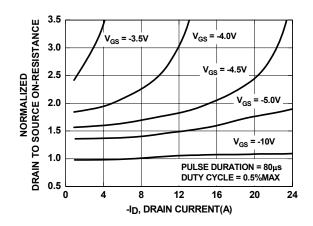


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

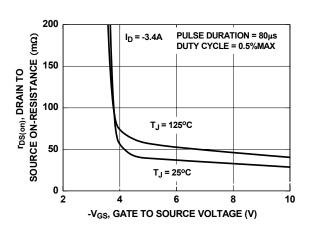


Figure 4. On-Resistance vs Gate to Source Voltage

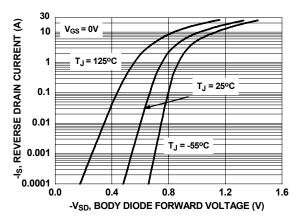


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics $T_J = 25^{\circ}C$ unless otherwise noted

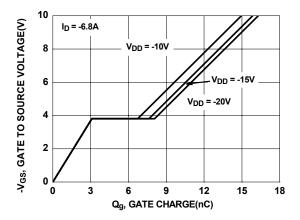


Figure 7. Gate Charge Characteristics

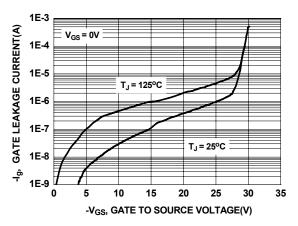


Figure 9. Gate Leakage Current vs Gate to Source Voltage

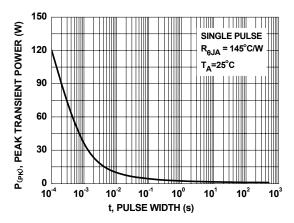


Figure 11. Single Pulse Maximum Power Dissipation

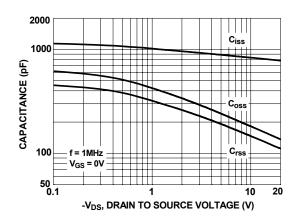


Figure 8. Capacitance vs Drain to Source Voltage

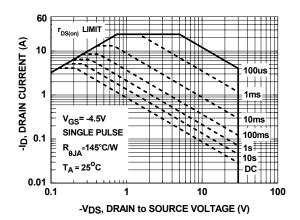


Figure 10. Forward Bias Safe Operating Area

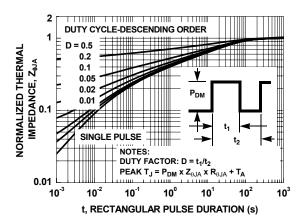
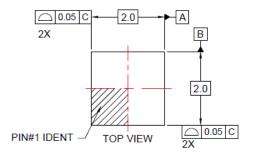
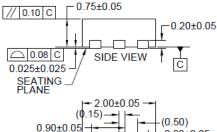
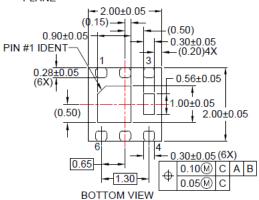


Figure 12. Transient Thermal Response Curve

Dimensional Outline and Pad Layout

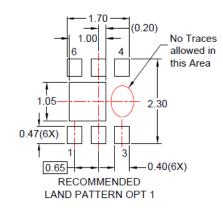


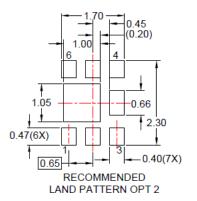




NOTES:

- A. PACKAGE DOES NOT FULLY CONFORM TO JEDEC MO-229 REGISTRATION
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009.
- D. LAND PATTERN RECOMMENDATION IS EXISTING INDUSTRY LAND PATTERN.
- E. DRAWING FILENAME: MKT-MLP06Lrev4.







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